

DESCRIPTION

The SPN4392W is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching.

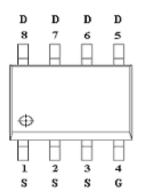
FEATURES

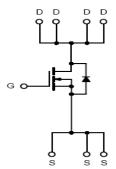
- 30V/13A, RDS(ON)= $8m\Omega(a)V$ GS=10V
- 30V/10A, RDS(ON)= $12m\Omega$ @VGS=4.5V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ♦ SOP 8P package design

APPLICATIONS

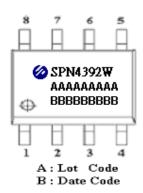
- Power Management in Note book
- Portable Equipment
- Battery Powered System
- High-Side DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

PIN CONFIGURATION(SOP – 8P)





PART MARKING



2011/06/03 **Ver.1**

PIN DESCRIPTION						
Pin	Symbol	Description				
1	S	Source				
2	S	Source				
3	S	Source				
4	G	Gate				
5	D	Drain				
6	D	Drain				
7	D	Drain				
8	D	Drain				

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN4392WS8RGB	SOP- 8P	SPN4392W

[※] SPN4392WS8RGB: 13" Tape Reel; Pb − Free; Halogen - Free

ABSOULTE MAXIMUM RATINGS

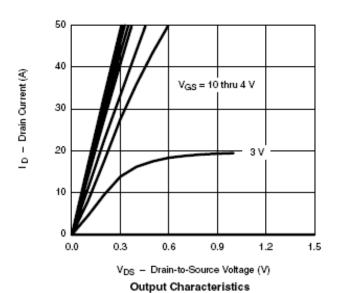
(TA=25°C Unless otherwise noted)

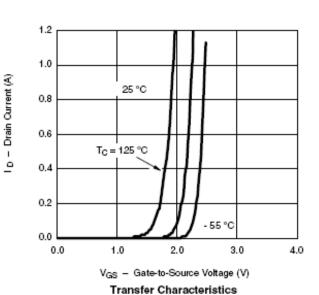
Parameter	Symbol	Typical	Unit	
Drain-Source Voltage	Vdss	30	V	
Gate –Source Voltage	VGSS	±20	V	
Continuous Drain Current(Tj=150°C)	TA=25°C	In	13	Α
Continuous Diani Current(13–130 C)	Ta=70°C	ID	10	A
Pulsed Drain Current		Ірм	50	Α
Continuous Source Current(Diode Conduct	Is	5.6	А	
Power Dissination	TA=25°C	PD	2.5	W
Power Dissipation	Ta=70°C	PD	1.6	VV
Operating Junction Temperature		Тл	-55/150	°C
Storage Temperature Range	Tstg	-55/150	$^{\circ}$ C	
Thermal Resistance-Junction to Ambient		RθJA	80	°C/W

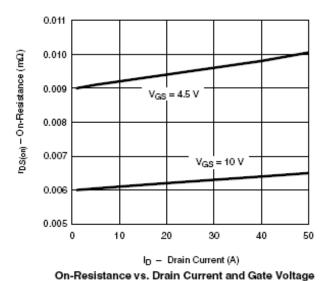
ELECTRICAL CHARACTERISTICS

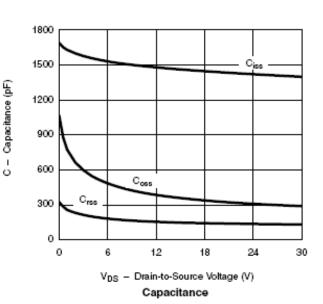
(Ta=25°C Unless otherwise noted)

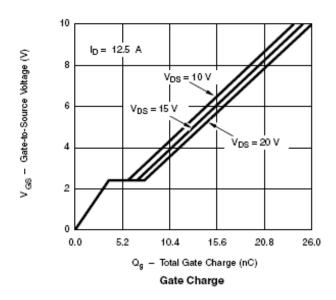
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage V(BR)D		$V_{GS} = 0V$, $I_D = 250uA$	30			V	
Gate Threshold Voltage	VGS(th)	$V_{DS} = V_{GS}, I_{DS} = 250uA$ 1.0			2.0	V	
Gate Leakage Current	Igss	$V_{DS} = 0V, V_{GS} = \pm 20 \text{ V}$			±100	nA	
		$V_{DS} = 30V, V_{GS} = 0V$			1		
Zero Gate Voltage Drain Current	Idss	$V_{DS} = 30V, V_{GS} = 0V,$ $T_J = 125C$			100	uA	
Drain-Source On-Resistance	RDS(on)	$V_{GS} = 10V$, $ID = 13A$		0.006	0.008	Ω	
		$V_{GS} = 4.5V, ID = 10A$		0.009	0.012		
Forward Transconductance	gfs	$V_{DS} = 15V, I_{D} = 20 A$	10			S	
Diode Forward Voltage	V_{SD}	$I_F = 13 \text{ A}, V_{GS} = 0V$		1.0	1.5	V	
Dynamic							
Total Gate Charge	Qg			12	20		
Gate-Source Charge	Qgs	$V_{DS} = 15V, V_{GS} = 5V,$ $I_{D} = 13 \text{ A}$		4		nC	
Gate-Drain Charge	Qgd	1571		5			
Input Capacitance	Ciss			1500			
Output Capacitance	Coss	$V_{GS} = 0V$, $V_{DS} = 25V$, F=1MHz		320		pF	
Reverse Transfer Capacitance	Crss	1111112		200			
Turn-On Time	td(on)			8	12		
Turn-On Time	tr	$(V_{DD} = 15 \text{ V}, I_D = 13 \text{ A},$		10	15	12 G	
Trum Off Time o	td(off)	$V_{GS}=10V,R_G=2.5\Omega)$		18	30	ns	
Turn-Off Time	tf			6	9		

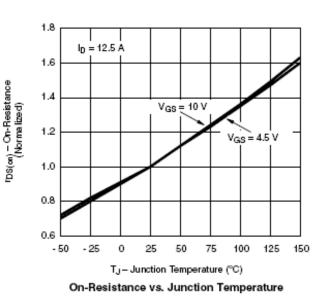


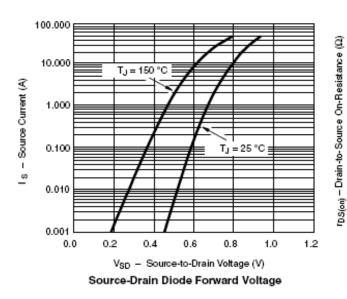


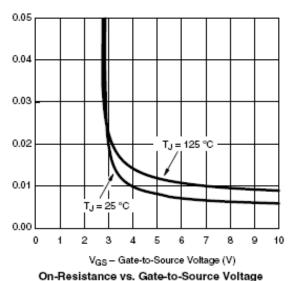




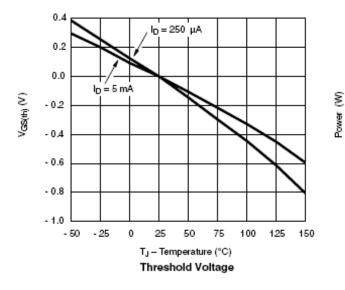


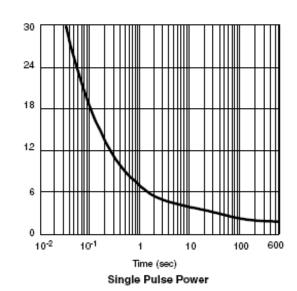


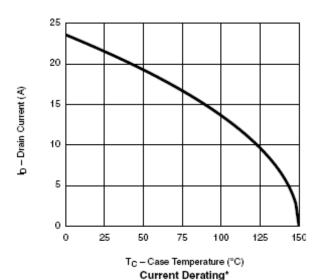


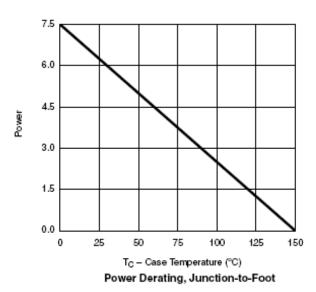


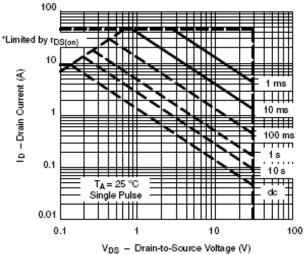
On-nesistance vs. Gate-to-Source voltage







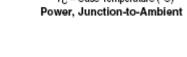


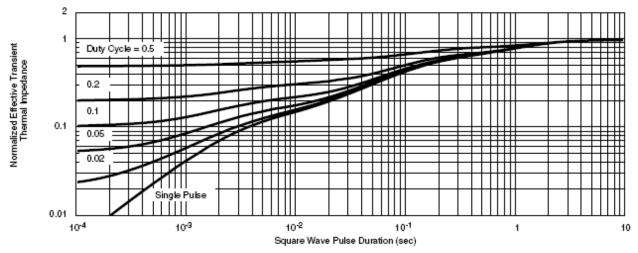


1.70
1.36
1.02
0.68
0.34
0.00
0 25 50 75 100 125 150
T_C - Case Temperature (°C)

V_{DS} - Drain-to-Source Voltage (V)

*V_{GS} > minimum V_{GS} at which r_{DS(on)} is specified
Safe Operating Area, Junction-to-Ambient

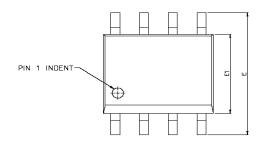


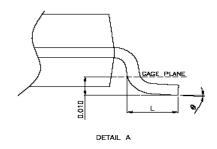


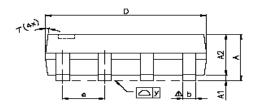
Normalized Thermal Transient Impedance, Junction-to-Foot

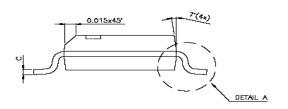


SOP- 8 PACKAGE OUTLINE









0.4.50.0	DIMENSIONS IN MILLIMETERS		DIMENSIONS IN INCHES			
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10		0.25	0.004		0.010
A2		1.45			0.057	
Ь	0.33	0.41	0.51	0.013	0.016	0.020
С	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
Е	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
е		1.27			0.050	
L	0.38	0.71	1.27	0.015	0.028	0.050
<u>∕</u> 2 y			0.076			0.003
0	0,		8*	0,		8*

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